

Bridge Rectifiers GBU8A - GBU8M

Features

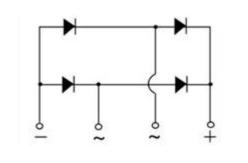
- Glass-Passivated Junction
- Surge Overload Rating: 200 A Peak
- Reliable Low-Cost Construction Utilizing Molded Plastic Technique
- Ideal for Printed Circuit Board
- UL Certified: UL #E258596

PACKAGE MARKING AND ORDERING INFORMATION

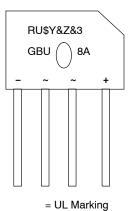
Part Number	Marking	Package	Packing Method
GBU8A	GBU8A	GBU 4L	Rail
GBU8B	GBU8B		
GBU8D	GBU8D		
GBU8G	GBU8G		
GBU8J	GBU8J		
GBU8K	GBU8K		
GBU8M	GBU8M		



CASE 127EL



MARKING DIAGRAM



RU \$Y

= ON Semiconductor Logo = Assembly Plant Code

&Z &3 = Numeric Date Code GBU8A

= Specific Device Code

GBU8A - GBU8M

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

			Value							
Symbol	Parameter		8A	8B	8D	8G	8J	8K	8M	Units
V _{RRM}	Maximum Repetitive Reverse Voltage		50	100	200	400	600	800	1000	V
V _{RMS}	Maximum RMS Bridge Input Voltage		35	70	140	280	420	560	700	V
V _R	DC Reverse Voltage (Rated V _R)		50	100	200	400	600	800	1000	V
I _{F(AV)}	Average Rectified Forward	T _A = 100°C	8.0					Α		
	Current	T _A = 45°C	6.0						Α	
I _{FSM}	Non-Repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave		200					Α		
T _{STG}	Storage Temperature Range		-55 to +150					°C		
TJ	Operating Junction Temperature		-55 to +150				°C			

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARECTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Value	Units
P _D	Power Dissipation	16	W
$R_{ heta JA}$	Thermal Resistance per Leg, Junction to Ambient (Note 1)	18	°C/W
$R_{ heta JL}$	Thermal Resistance per Leg, Junction to Case (Note 2)	3	°C/W

^{1.} Device mounted on PCB with 0.5×0.5 inch $(12 \times 12 \text{ mm})$

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Symbol	Parameter	Value	Units	
V _F	Forward Voltage, per Element	8.0 A	1.0	V
I _R	Reverse Current, per Element at Rated V _R	T _A = 25°C	5.0	μΑ
		T _A = 100°C	500	μΑ
I ² t	I ² t Rating for Fusing	t < 8.35 ms	166	A ² s

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{2.} Heat sink mounting, $4 \times 4 \times 0.15$ inch copper plate

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TYPICAL PERFORMANCE CHARACTERISTICS

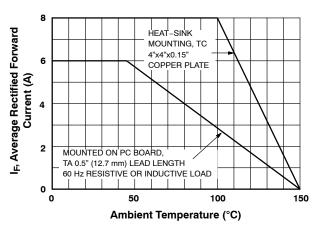


Figure 1. Forward Current Derating Curve

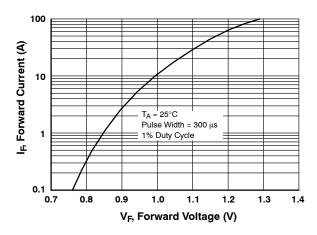


Figure 2. Forward Voltage Characteristics

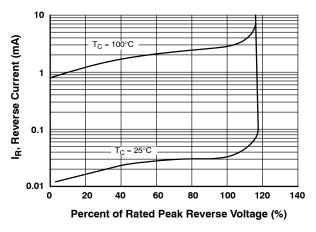


Figure 3. Reverse Current vs. Reverse Voltage

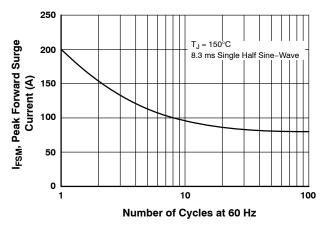
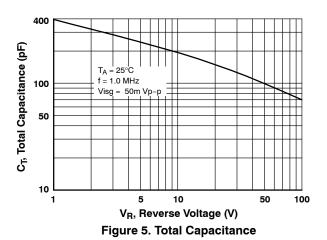
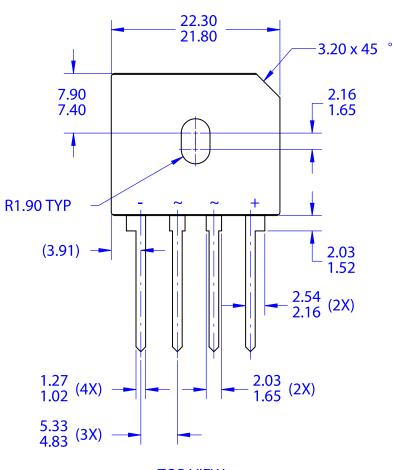


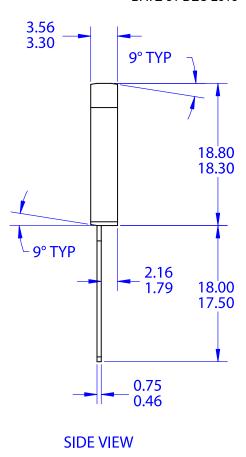
Figure 4. Non-Repetitive Surge Current



SIP4 22.05x18.55 CASE 127EL ISSUE O

DATE 31 DEC 2016





TOP VIEW

NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE
- **B. ALL DIMENSIONS ARE IN MILLIMETERS**
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- D. DIMENSIONS AND TOLERANCES AS PER ASME Y14.5-2009

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